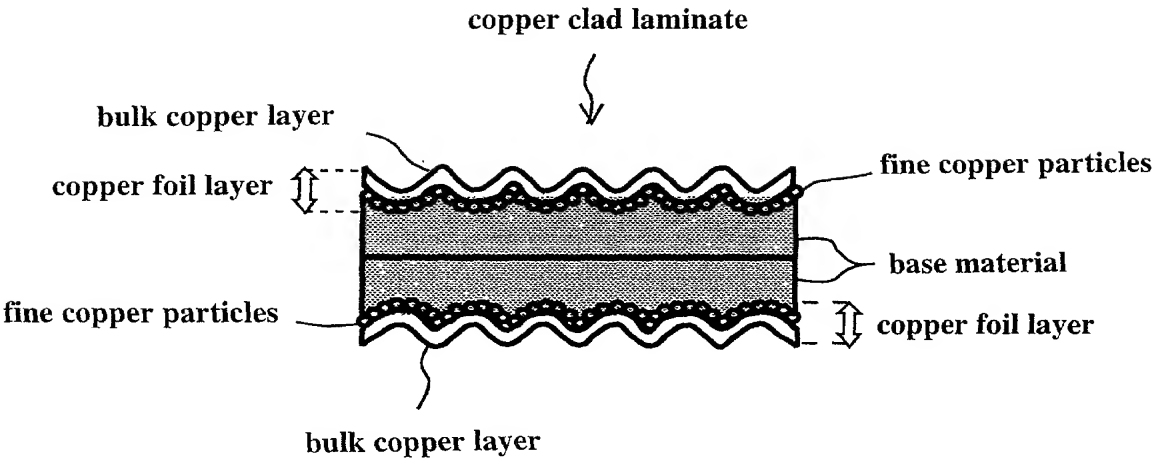
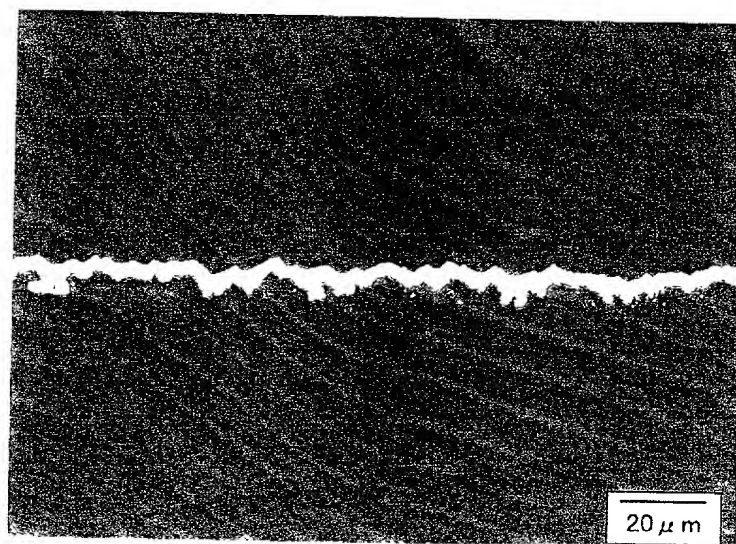


FIG. 1



09255382 051504

FIG. 2



0985333 051601
105750 2825860

FIG. 3

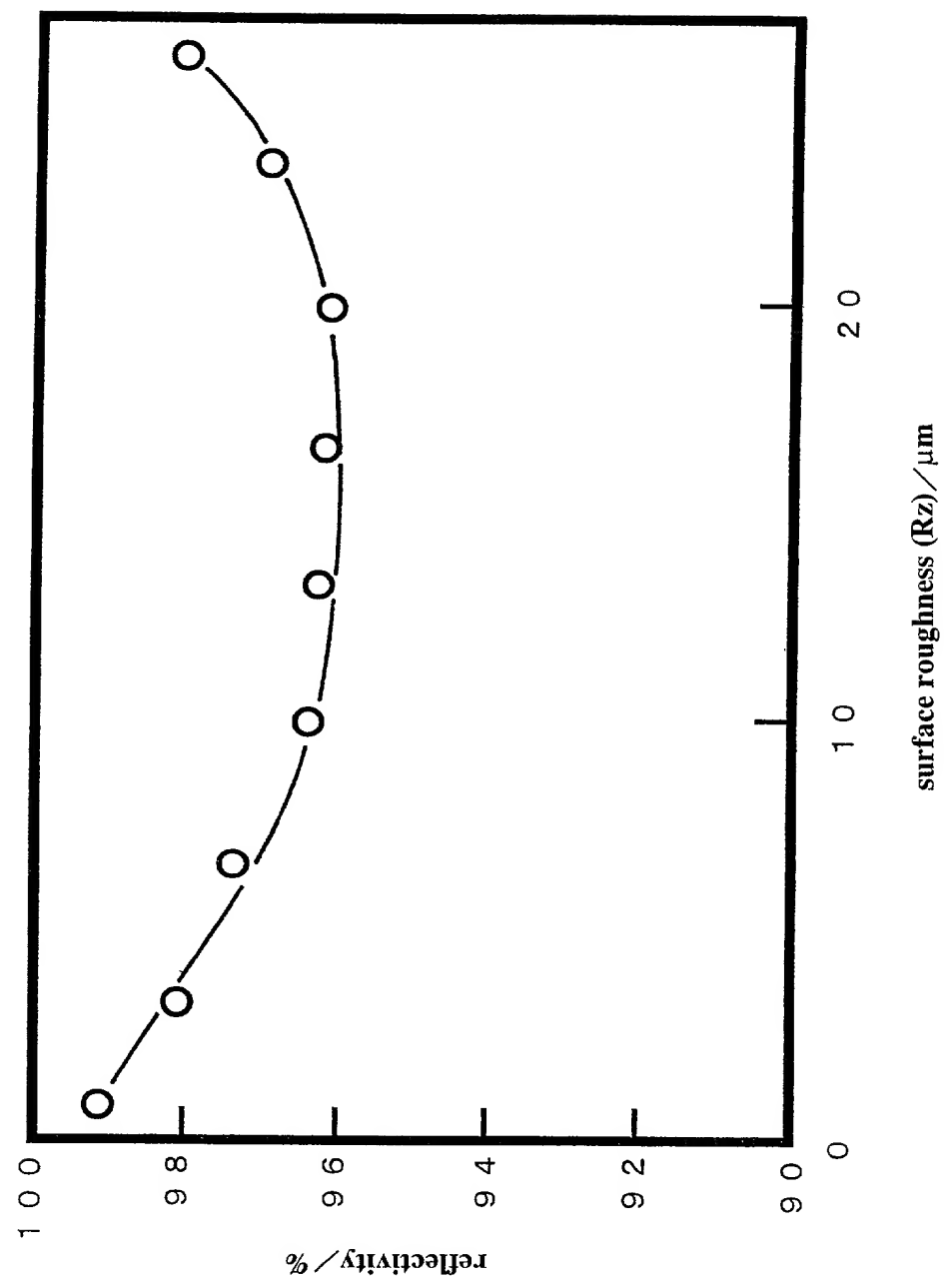
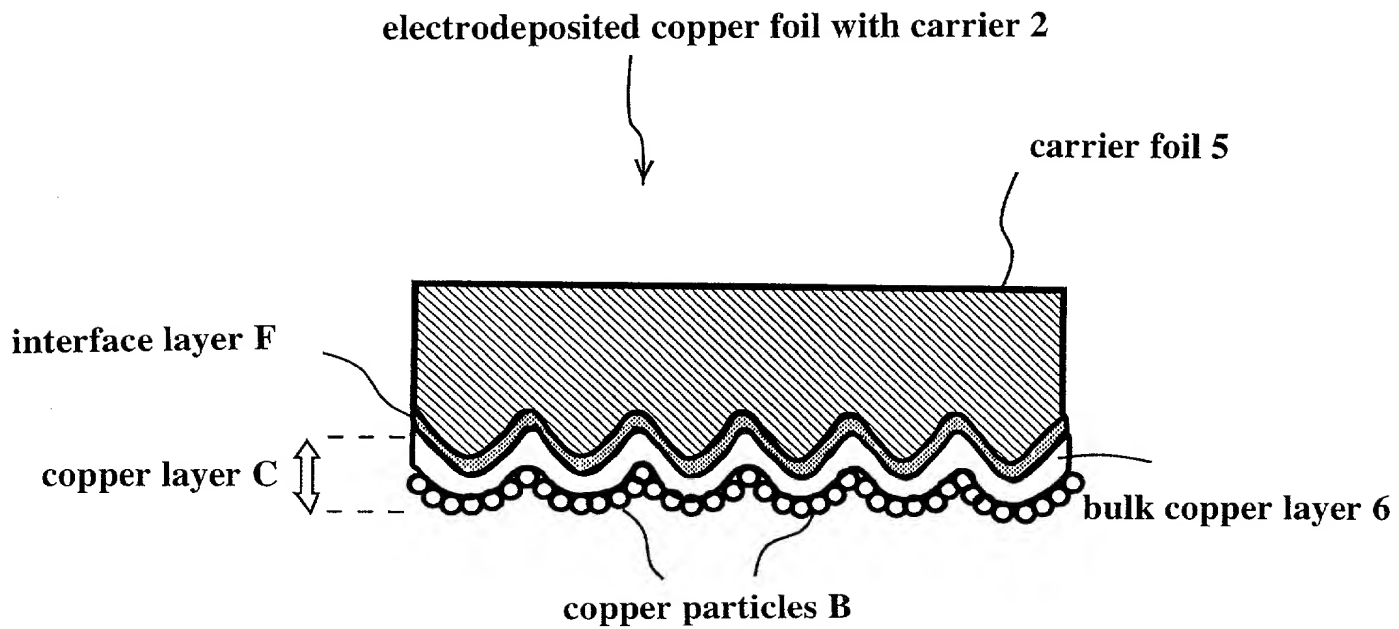


FIG. 4



09855382-051501
T05T50-2855560

FIG. 5

(a) Manufacturing of copper clad laminate

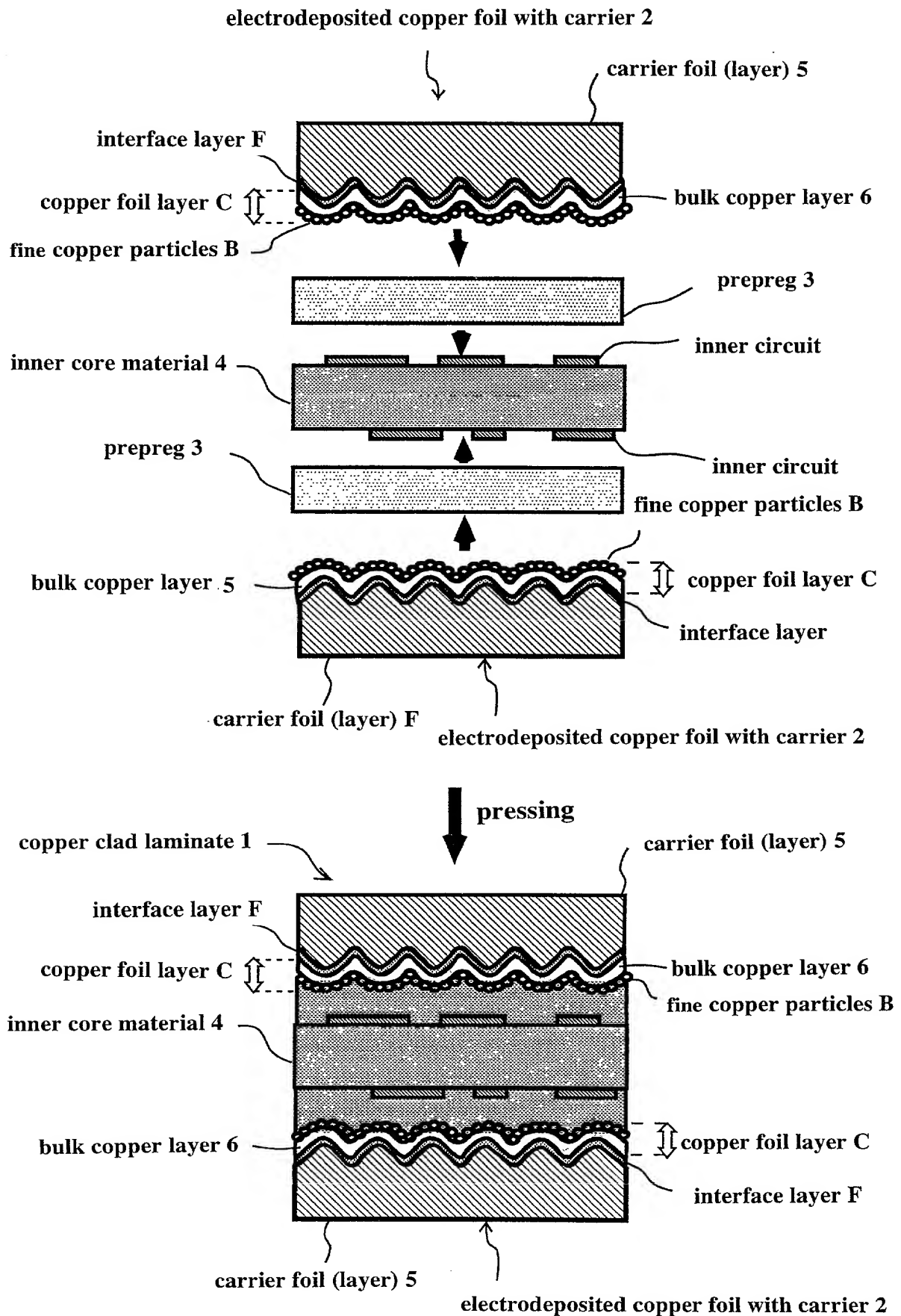
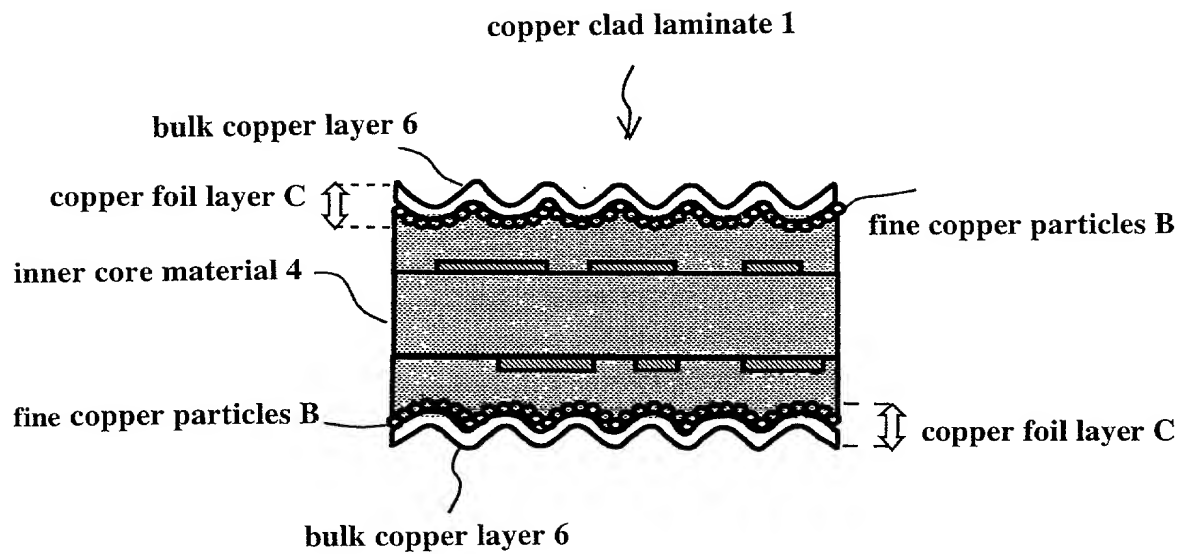


FIG. 6

(b) Peeling of Carrier Foil



(c) Laser Treatment for Forming Holes

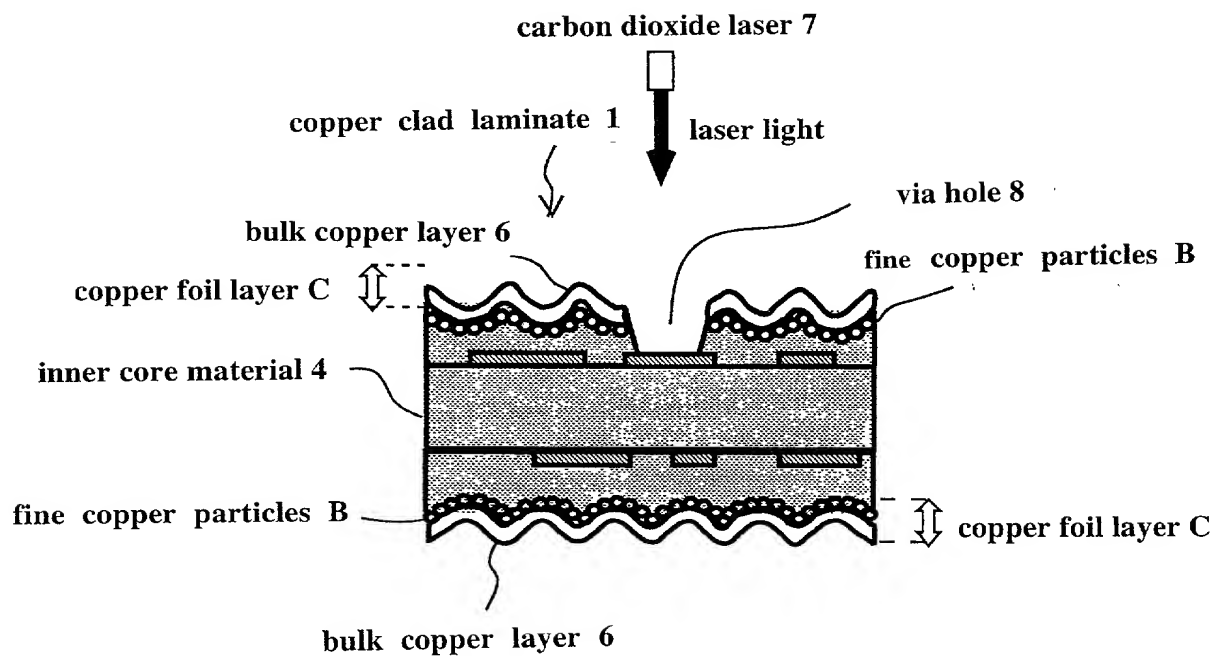
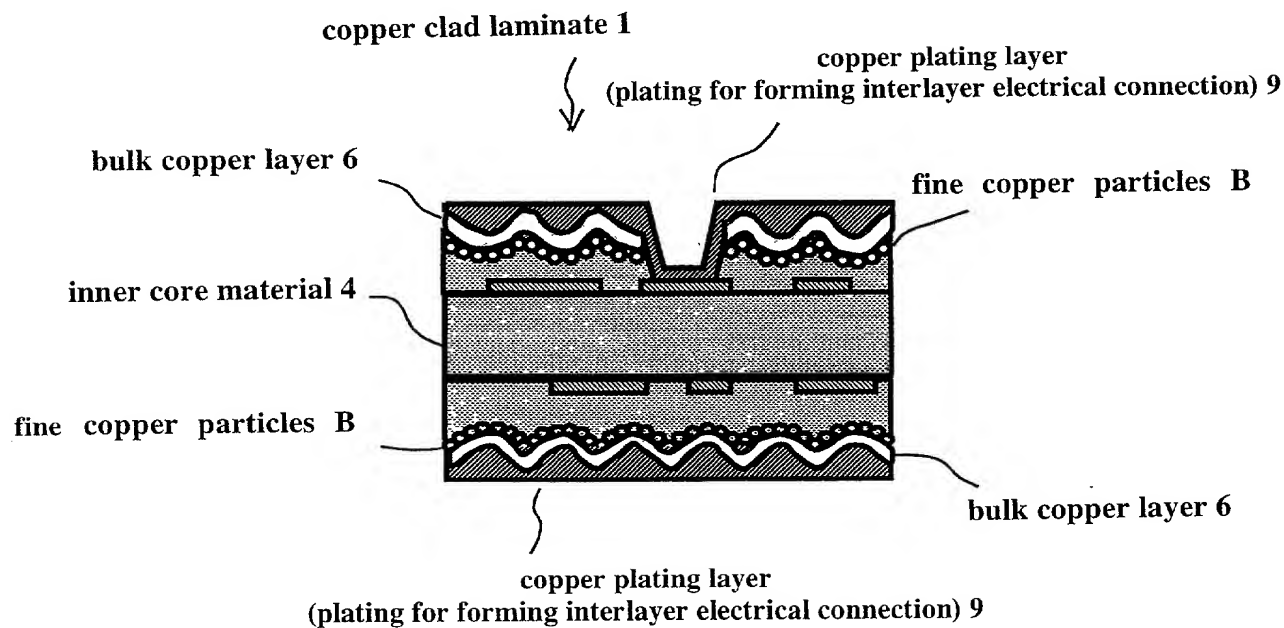


FIG. 7

(d) Copper Plating for Forming Interlayer Electrical Connection



(e) Forming Etching Resist Layers

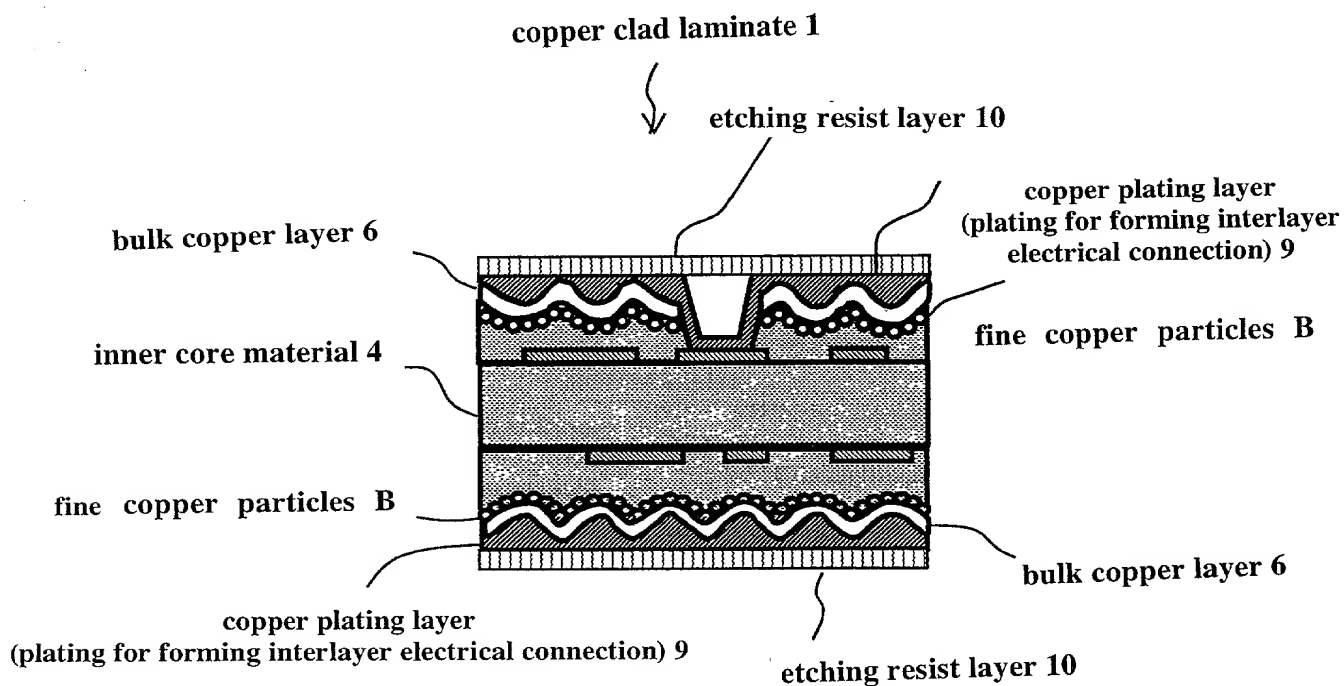
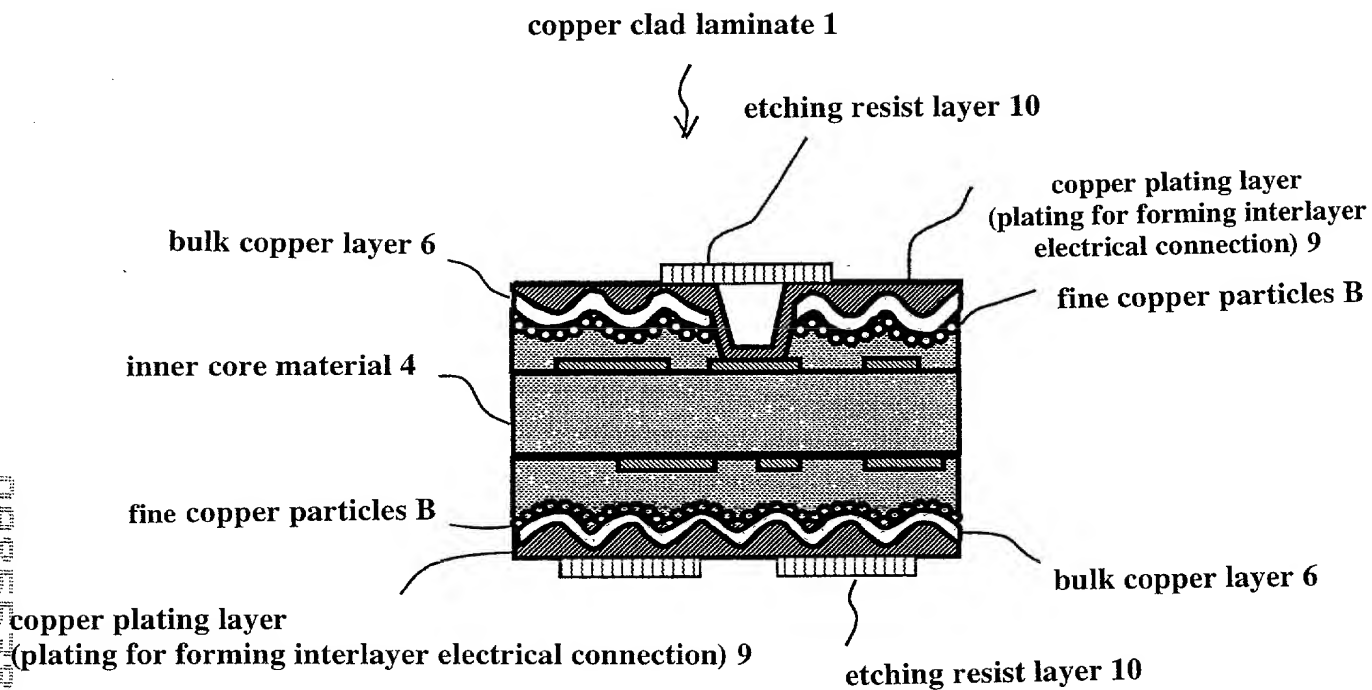


FIG. 8

(f) Exposing and Developing the Etching Resist Layers



(g) Copper Etching

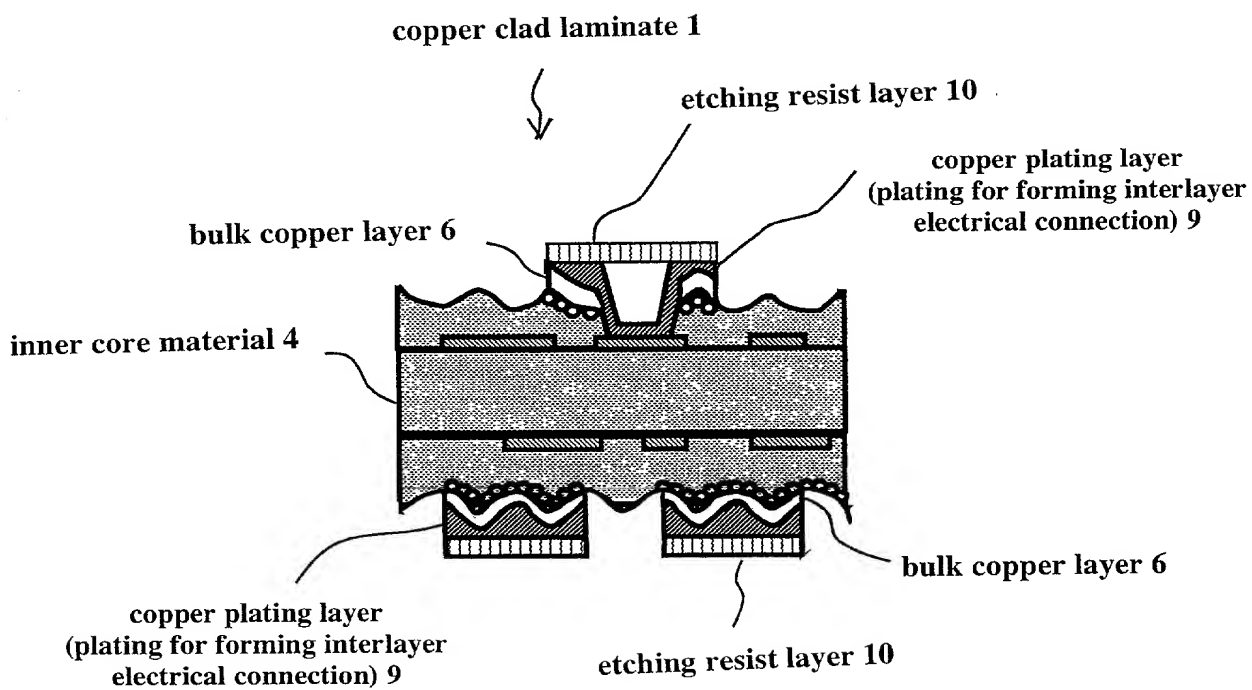


FIG. 9

(h) Peering of Etching Resist Layers

